Schottky Rectifier, 1 A

PRODUCT SUMMARY	
$I_{F(AV)}$	1.0 A
V_R	100 V

FEATURES

- Small foot print, surface mountable
- Low forward voltage drop
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- Lead (Pb)-free (“PbF” suffix)
- Designed and qualified for industrial level

DESCRIPTION

The 10BQ100PbF surface mount Schottky rectifier has been designed for applications requiring low forward drop and very small foot prints on PC boards. Typical applications are in disk drives, switching power supplies, converters, freewheeling diodes, battery charging, and reverse battery protection.

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum forward voltage drop See fig. 1	V_{FM} (1)	1 A	T_J = 25 °C	0.78	V
		2 A		0.89	
		1 A	T_J = 125 °C	0.62	
		2 A		0.72	
Maximum reverse leakage current See fig. 2	I_{RM} (1)	T_J = 25 °C	V_R = Rated V_R	0.5	mA
		T_J = 125 °C		1	
Typical junction capacitance	C_T	V_R = 5 V_{DC}, (test signal range 100 kHz to 1 MHz) 25 °C		42	pF
Typical series inductance	L_S	Measured lead to lead 5 mm from package body		2.0	nH
Maximum voltage rate of charge	dV/dt	Rated V_R		10 000	V/µs

Note

(1) Pulse width < 300 µs, duty cycle < 2 %

THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T_J (1), T_{Stg}		- 55 to 175	°C
Maximum thermal resistance, junction to lead	R_{thJL} (2)	DC operation	36	°C/W
Maximum thermal resistance, junction to ambient	R_{thJA}		80	
Approximate weight			0.10	g
			0.003	oz.
Marking device		Case style SMB (similar DO-214AA)	V1J	

Notes

(1) $\frac{dP_{tot}}{dT_J} < \frac{1}{R_{thJA}}$ thermal runaway condition for a diode on its own heatsink

(2) Mounted 1" square PCB

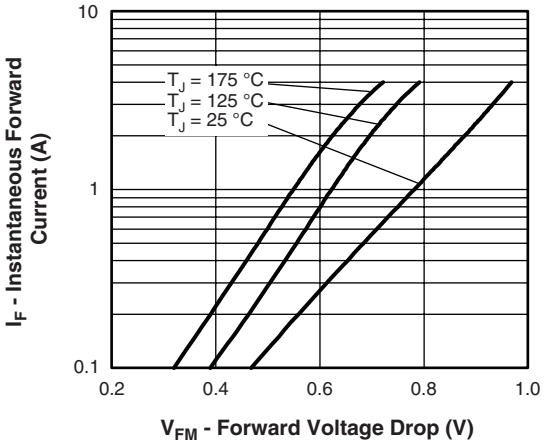


Fig. 1 - Maximum Forward Voltage Drop Characteristics

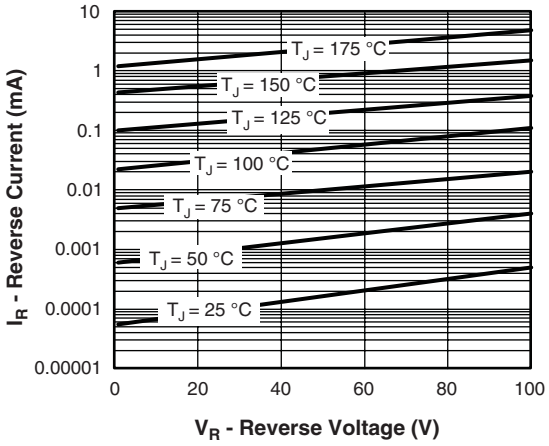


Fig. 2 - Typical Peak Reverse Current vs. Reverse Voltage

100

Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

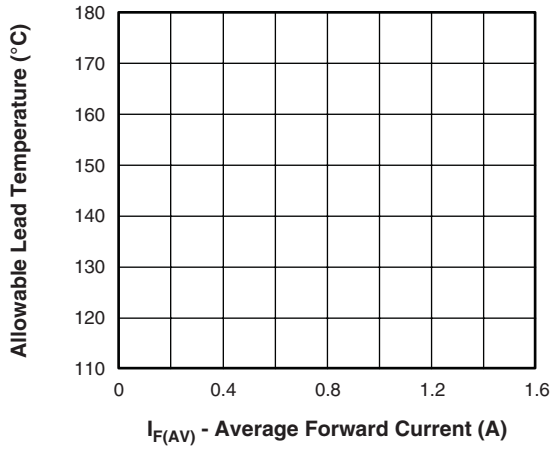


Fig. 5 - Maximum Average Forward Current vs. Allowable Lead Temperature

Fig. 6 - Maximum Average Forward Dissipation vs. Average Forward Current

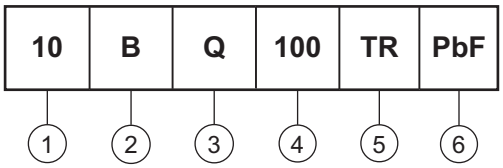
Fig. 7 - Maximum Peak Surge Forward Current vs. Pulse Duration

Note

(1) Formula used: $T_C = T_J - (Pd + Pd_{REV}) \times R_{thJC}$;
Pd = Forward power loss = $I_{F(AV)} \times V_{FM}$ at ($I_{F(AV)}$/D) (see fig. 6);
Pd_{REV} = Inverse power loss = $V_{R1} \times I_R$ (1 - D); I_R at V_{R1} = 80 % rated V_R

ORDERING INFORMATION TABLE

Device code



1 - Current rating

2 - B = Single lead diode

3 - Q = Schottky "Q" series

4 - Voltage rating (100 = 100 V)

5 - • None = Bulk (1000 pieces)
• TR = Tape and reel (3000 pieces)

6 - • None = Standard production
• PbF = Lead (Pb)-free

LINKS TO RELATED DOCUMENTS	
Dimensions	http://www.vishay.com/doc?95017
Part marking information	http://www.vishay.com/doc?95029
Packaging information	http://www.vishay.com/doc?95034
SPICE model	http://www.vishay.com/doc?95276

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